REMARKS

The specification has been amended to correct errors of a typographical and

grammatical nature. Due to the number of corrections thereto, applicants submit herewith a

Substitute Specification, along with a marked-up copy of the original specification for the

Examiner's convenience. The substitute specification includes the changes as shown in the

marked-up copy and includes no new matter. Therefore, entry of the Substitute Specification

is respectfully requested.

The abstract has also been amended to more clearly describe the features of the

present invention.

Also submitted herewith is a proposed amendment to the drawings, wherein Figs. 5, 6,

8 - 10, 12 - 16 and 21 have been amended at this time. Upon receipt of the approval of the

amendment to the drawings and receipt of a Notice of Allowance, the proposed drawing

corrections will be effected in accordance with present practice.

Entry of the preliminary amendments and examination of the application is

respectfully requested.

To the extent necessary, applicant's petition for an extension of time under 37 CFR

1.136. Please charge any shortage in the fees due in connection with the filing of this paper,

including extension of time fees, to Deposit Account No. 01-2135 (501.40475X00) and

please credit any excess fees to such deposit account.

Respectfully submitted,

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ABSTRACT OF THE DISCLOSURE

A method and its apparatus for inspecting a semiconductor device in which failure occurrence conditions on a whole wafer are estimated by calculating the statistic of potential contrasts in pattern sections from sampled images to implement higher throughput, and defective conditions of a process are detected at an early stage with the help of time series data of the estimated result.